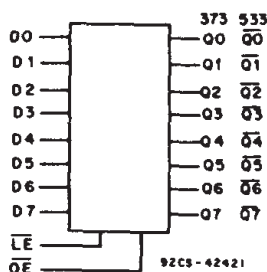


CD54/74AC373, CD54/74AC533 CD54/74ACT373, CD54/74ACT533



Data sheet acquired from Harris Semiconductor
SCHS289



FUNCTIONAL DIAGRAM

Octal Transparent Latch, 3-State

CD54/74AC/ACT373 - Non-Inverting

CD54/74AC/ACT533 - Inverting

Type Features:

- Buffered inputs
- Typical propagation delay:
4.3 ns @ $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$, $C_L = 50\text{ pF}$

The RCA-CD54/74AC373 and CD54/74AC533 and the CD54/74ACT373 and CD54/74ACT533 octal transparent 3-state latches use the RCA ADVANCED CMOS technology. The outputs are transparent to the inputs when the Latch Enable ($\overline{LE}$) is HIGH. When the Latch Enable ($\overline{LE}$) goes LOW, the data is latched. The Output Enable ($\overline{OE}$) controls the 3-state outputs. When the Output Enable ($\overline{OE}$) is HIGH, the outputs are in the high-impedance state. The latch operation is independent of the state of the Output Enable.

The CD74AC/ACT373 and CD74AC/ACT533 are supplied in 20-lead dual-in-line plastic packages (E suffix) and in 20-lead dual-in-line small-outline plastic packages (M suffix). Both package types are operable over the following temperature ranges: Commercial (0 to 70°C); Industrial (-40 to $+85^\circ\text{C}$); and Extended Industrial/Military (-55 to $+125^\circ\text{C}$).

The CD54AC/ACT373 and CD54AC/ACT533, available in chip form (H suffix), are operable over the -55 to $+125^\circ\text{C}$ temperature range.

Family Features:

- Exceeds 2-kV ESD Protection - MIL-STD-883, Method 3015
- SCR-Latchup-resistant CMOS process and circuit design
- Speed of bipolar FAST[®]/AS/S with significantly reduced power consumption
- Balanced propagation delays
- AC types feature 1.5-V to 5.5-V operation and balanced noise immunity at 30% of the supply
- $\pm 24\text{-mA}$ output drive current
 - Fanout to 15 FAST[®] ICs
 - Drives 50-ohm transmission lines

*FAST is a Registered Trademark of Fairchild Semiconductor Corp.

TRUTH TABLE

Output Enable	Latch Enable	Data	AC/ACT373 Output	AC/ACT533 Output
L	H	H	H	L
L	H	L	L	H
L	L	I	L	H
L	L	h	H	L
H	X	X	Z	Z

Note:

L = Low voltage level
H = High voltage level
I = Low voltage level one set-up time prior to the high to low latch enable transition

h = High voltage level one set-up time prior to the high to low latch enable transition.
X = Don't Care
Z = High Impedance State

Technical Data

CD54/74AC373, CD54/74AC533

CD54/74ACT373, CD54/74ACT533

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE (V_{CC})	-0.5 to 6 V
DC INPUT DIODE CURRENT, I_{IK} (for $V_i < -0.5$ V or $V_i > V_{CC} + 0.5$ V)	± 20 mA
DC OUTPUT DIODE CURRENT, I_{OK} (for $V_o < -0.5$ V or $V_o > V_{CC} + 0.5$ V)	± 50 mA
DC OUTPUT SOURCE OR SINK CURRENT per Output Pin, I_o (for $V_o > -0.5$ V or $V_o < V_{CC} + 0.5$ V)	± 50 mA
DC V_{CC} or GROUND CURRENT (I_{CC} or I_{GND})	± 100 mA*
POWER DISSIPATION PER PACKAGE (P_D):	
For $T_A = -55$ to $+100^\circ\text{C}$ (PACKAGE TYPE E)	500 mW
For $T_A = +100$ to $+125^\circ\text{C}$ (PACKAGE TYPE E)	Derate Linearly at 8 mW/ $^\circ\text{C}$ to 300 mW
For $T_A = -55$ to $+70^\circ\text{C}$ (PACKAGE TYPE M)	400 mW
For $T_A = +70$ to $+125^\circ\text{C}$ (PACKAGE TYPE M)	Derate Linearly at 6 mW/ $^\circ\text{C}$ to 70 mW
OPERATING-TEMPERATURE RANGE (T_A)	-55 to $+125^\circ\text{C}$
STORAGE TEMPERATURE (T_{stg})	-65 to $+150^\circ\text{C}$
LEAD TEMPERATURE (DURING SOLDERING):	
At distance 1/16 $\pm$ 1/32 in. (1.59 $\pm$ 0.79 mm) from case for 10 s maximum	$+265^\circ\text{C}$
Unit inserted into PC board min. thickness 1/16 in. (1.59 mm) with solder contacting lead tips only	$+300^\circ\text{C}$

*For up to 4 outputs per device; add ± 25 mA for each additional output.

RECOMMENDED OPERATING CONDITIONS:

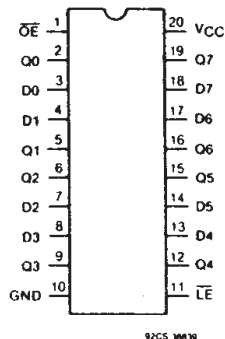
For maximum reliability, normal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range, V_{CC} *: (For T_A = Full Package-Temperature Range) AC Types ACT Types	1.5 4.5	5.5 5.5	V
DC Input or Output Voltage, V_i , V_o	0	V_{CC}	V
Operating Temperature, T_A	-55	+125	$^\circ\text{C}$
Input Rise and Fall Slew Rate, dt/dv at 1.5 V to 3 V (AC Types) at 3.6 V to 5.5 V (AC Types) at 4.5 V to 5.5 V (ACT Types)	0 0 0	50 20 10	ns/V ns/V ns/V

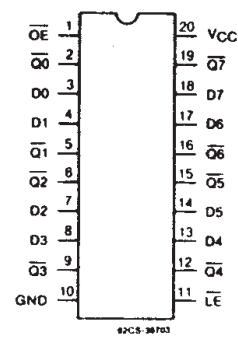
*Unless otherwise specified, all voltages are referenced to ground.

9

TERMINAL ASSIGNMENT DIAGRAMS



CD54/74AC373, CD54/74ACT373



CD54/74AC533, CD54/74ACT533

CD54/74AC373, CD54/74AC533 **CD54/74ACT373, CD54/74ACT533**

STATIC ELECTRICAL CHARACTERISTICS: AC Series

CHARACTERISTICS	TEST CONDITIONS		V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C						UNITS
				+25		-40 to +85		-55 to +125		
	V _I (V)	I _O (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage V _{IH}			1.5	1.2	—	1.2	—	1.2	—	V
			3	2.1	—	2.1	—	2.1	—	
			5.5	3.85	—	3.85	—	3.85	—	
Low-Level Input Voltage V _{IL}			1.5	—	0.3	—	0.3	—	0.3	V
			3	—	0.9	—	0.9	—	0.9	
			5.5	—	1.65	—	1.65	—	1.65	
High-Level Output Voltage V _{OH}	V _{IH} or V _{IL}	-0.05	1.5	1.4	—	1.4	—	1.4	—	V
		-0.05	3	2.9	—	2.9	—	2.9	—	
		-0.05	4.5	4.4	—	4.4	—	4.4	—	
		-4	3	2.58	—	2.48	—	2.4	—	
		-24	4.5	3.94	—	3.8	—	3.7	—	
	#, * {	-75	5.5	—	—	3.85	—	—	—	
		-50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage V _{OL}	V _{IH} or V _{IL}	0.05	1.5	—	0.1	—	0.1	—	0.1	V
		0.05	3	—	0.1	—	0.1	—	0.1	
		0.05	4.5	—	0.1	—	0.1	—	0.1	
		12	3	—	0.36	—	0.44	—	0.5	
		24	4.5	—	0.36	—	0.44	—	0.5	
	#, * {	75	5.5	—	—	—	1.65	—	—	
		50	5.5	—	—	—	—	—	1.65	
Input Leakage Current I _I	V _{CC} or GND		5.5	—	±0.1	—	±1	—	±1	μA
3-State Leakage Current I _{OZ}	V _{IH} or V _{IL} V _O = V _{CC} or GND		5.5	—	±0.5	—	±5	—	±10	μA
Quiescent Supply Current, MSI I _{CC}	V _{CC} or GND	0	5.5	—	8	—	80	—	160	μA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

Technical Data

CD54/74AC373, CD54/74AC533 CD54/74ACT373, CD54/74ACT533

STATIC ELECTRICAL CHARACTERISTICS: ACT Series

CHARACTERISTICS	TEST CONDITIONS		V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C						UNITS
	V _I (V)	I _O (mA)		+25		-40 to +85		-55 to +125		
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage V _{IH}			4.5 to 5.5	2	—	2	—	2	—	V
Low-Level Input Voltage V _{IL}			4.5 to 5.5	—	0.8	—	0.8	—	0.8	V
High-Level Output Voltage V _{OH}	V _{IH} or V _{IL} # , * {	-0.05	4.5	4.4	—	4.4	—	4.4	—	V
		-24	4.5	3.94	—	3.8	—	3.7	—	
		-75	5.5	—	—	3.85	—	—	—	
		-50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage V _{OL}	V _{IH} or V _{IL} # , * {	0.05	4.5	—	0.1	—	0.1	—	0.1	V
		24	4.5	—	0.36	—	0.44	—	0.5	
		75	5.5	—	—	—	1.65	—	—	
		50	5.5	—	—	—	—	—	1.65	
Input Leakage Current I _I	V _{CC} or GND		5.5	—	±0.1	—	±1	—	±1	μA
3-State Leakage Current I _{OZ}	V _{IH} or V _{IL} V _O = V _{CC} or GND		5.5	—	±0.5	—	±5	—	±10	μA
Quiescent Supply Current, MSI I _{CC}	V _{CC} or GND	0	5.5	—	8	—	80	—	160	μA
Additional Quiescent Supply Current per Input Pin TTL Inputs High 1 Unit Load ΔI _{CC}	V _{CC} -2.1		4.5 to 5.5	—	2.4	—	2.8	—	3	mA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

ACT INPUT LOADING TABLE

INPUT	UNIT LOAD*	
	ACT373	ACT533
$\overline{OE}$	0.87	0.87
$\overline{Dn}$	0.5	0.5
$\overline{LE}$	0.8	0.8

*Unit load is ΔI_{CC} limit specified in Static Characteristics Chart, e.g., 2.4 mA max. @ 25°C.

CD54/74AC373, CD54/74AC533 **CD54/74ACT373, CD54/74ACT533**

PREREQUISITE FOR SWITCHING: AC Series

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
LE Pulse Width	t _w	1.5	44	—	50	—	ns
		3.3*	4.9	—	5.6	—	
		5†	3.5	—	4	—	
Setup Time Data to LE	t _{su}	1.5	2	—	2	—	ns
		3.3	2	—	2	—	
		5	2	—	2	—	
Hold Time Data to LE	t _H	1.5	33	—	38	—	ns
		3.3	3.7	—	4.2	—	
		5	2.6	—	3	—	

*3.3 V: min. is @ 3 V

†5 V: min. is @ 4.5 V

SWITCHING CHARACTERISTICS: AC Series; t_r, t_f = 3 ns, C_L = 50 pF

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Data to Qn 373	t _{PLH} t _{PHL}	1.5 3.3* 5†	— 3.1 2.2	96 10.8 7.7	— 3 2.1	106 11.9 8.5	ns
533	t _{PLH} t _{PHL}	1.5 3.3 5	— 3.8 2.7	119 13.4 9.5	— 3.7 2.6	131 14.7 10.5	ns
LE on Qn 373	t _{PLH} t _{PHL}	1.5 3.3 5	— 4.3 3.1	136 15.2 10.9	— 4.2 3	150 16.8 12	ns
533	t _{PLH} t _{PHL}	1.5 3.3 5	— 4.3 3.1	136 15.3 10.9	— 4.2 3	150 16.8 12	ns
Output Enable Times	t _{PZL} t _{PZH}	1.5 3.3 5	— 4.1 2.7	119 14.4 9.5	— 4 2.6	131 15.8 10.5	ns
Output Disable Times	t _{PLZ} t _{PHZ}	1.5 3.3 5	— 3.7 3	131 13.1 10.5	— 3.6 2.9	144 14.4 11.5	ns
Power Dissipation Capacitance	C _{PD} §	—	63 Typ.		63 Typ.		pF
Min. (Valley) V _{OH} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OHV} See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) V _{OL} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OLP} See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C _I	—	—	10	—	10	pF
3-State Output Capacitance	C _O	—	—	15	—	15	pF

*3.3 V: min. is @ 3.6 V
max. is @ 3 V

†5 V: min. is @ 5.5 V
max. is @ 4.5 V

§C_{PD} is used to determine the dynamic power consumption, per latch.

P_D = V_{CC}² f_i (C_{PD} + C_L) where f_i = input frequency

C_L = output load capacitance

V_{CC} = supply voltage.

Technical Data

CD54/74AC373, CD54/74AC533 CD54/74ACT373, CD54/74ACT533

PREREQUISITE FOR SWITCHING: ACT Series

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) -°C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
LE Pulse Width	t _w	5†	3.6	—	4	—	ns
Setup Time Data to LE	t _{su}	5	2	—	2	—	ns
Hold Time Data to LE	t _H	5	2.7	—	3	—	ns

†5 V: min. is @ 4.5 V

SWITCHING CHARACTERISTICS: ACT Series; t_r, t_f = 3 ns, C_L = 50 pF

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) -°C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Data to Q _n 373	t _{PLH}	5†	2.7	9.5	2.6	10.4	ns
533	t _{PHL}		3	10.4	2.9	11.4	
LE to Q _n 373 533	t _{PLH} t _{PHL}	5	3.1	11.4	3	12.5	ns
Output Enable Times	t _{PZL} t _{PZH}	5	3.5	12.3	3.4	13.5	ns
Output Disable Times	t _{PLZ} t _{PHZ}	5	3.2	11.4	3.1	12.5	ns
Power Dissipation Capacitance	C _{PD} §	—	63 Typ.		63 Typ.		pF
Min. (Valley) V _{OH} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OHV} See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) V _{OL} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OLP} See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C _I	—	—	10	—	10	pF
3-State Output Capacitance	C _O	—	—	15	—	15	pF

†5 V: min. is @ 5.5 V
max. is @ 4.5 V

§C_{PD} is used to determine the dynamic power consumption, per latch.

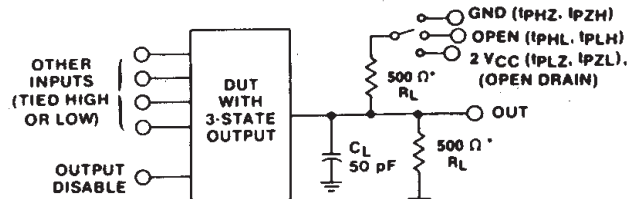
$P_D = V_{CC}^2 f_i (C_{PD} + C_L) + V_{CC} \Delta I_{CC}$ where f_i = input frequency
C_L = output load capacitance
V_{CC} = supply voltage.

9

The diagram shows two sets of waveforms. The top set, labeled "OTHER OUTPUTS", shows a solid line switching between V_{OH} and V_{OL} levels, with dashed lines indicating the transition region. The bottom set, labeled "OUTPUT UNDER TEST", shows a solid line with a glitch between V_{OLP} and V_{OL} levels, with dashed lines indicating the transition region. The glitch occurs while the output is at the V_{OL} level.

1. V_{OHV} AND V_{OLP} ARE MEASURED WITH RESPECT TO A GROUND REFERENCE NEAR THE OUTPUT UNDER TEST.
2. INPUT PULSES HAVE THE FOLLOWING CHARACTERISTICS:
 $PRR \leq 1 \text{ MHz}$, $t_r \approx 3 \text{ ns}$, $t_f \approx 3 \text{ ns}$, SKEW 1 ns .
3. R.F. FIXTURE WITH 700-MHz DESIGN RULES REQUIRED.
 IC SHOULD BE SOLDERED INTO TEST BOARD AND BYPASSED WITH $0.1 \mu\text{F}$ CAPACITOR. SCOPE AND PROBES REQUIRE 700-MHz BANDWIDTH.

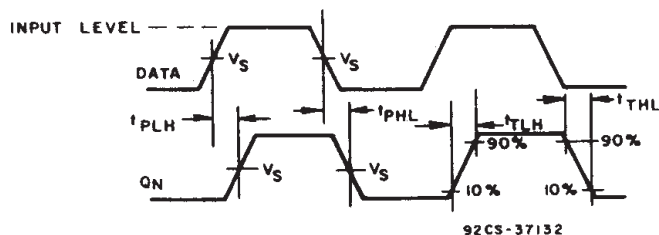
The diagram illustrates the timing characteristics of the 74ALS147 decoder. It shows the input level, output disable signal, and the outputs during enable and disable periods. Key parameters include $t_1 = 3 \text{ ns}$, $t_2 = 3 \text{ ns}$, t_{PLZ} , t_{PZH} , t_{PHZ} , and t_{PZL} . Voltage levels are marked at $90\% V_S$, V_S , $10\% V_S$, $0.2 V_{CC}$, and $0.8 V_{CC}$. The diagram is divided into three sections: OUTPUTS ENABLED, OUTPUTS DISABLED, and OUTPUTS ENABLED.



*FOR AC SERIES ONLY: WHEN $V_{CC} = 1.5 \text{ V}$, $R_L = 1 \text{ k}\Omega$

92CM-42405

Fig. 2 - Three-state propagation delay waveforms and test circuit.

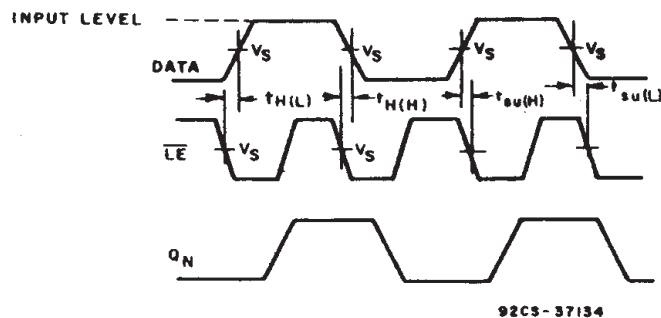


The timing diagram illustrates the relationship between the Input Level, Data, and the output signal Q_N . The Input Level signal is shown as a square wave with a high level V_S and a low level V . The Data signal is also a square wave with a high level V_S and a low level V . The output signal Q_N is a square wave that transitions from low to high when the Input Level transitions from low to high, and from high to low when the Input Level transitions from high to low. The timing parameters are defined as follows:

- V_S : Supply voltage level.
- V : Input signal level.
- t_w : Width of the input pulse.
- t_{PLH} : Propagation delay from the rising edge of the input signal to the rising edge of the output signal Q_N .
- t_{PHL} : Propagation delay from the falling edge of the input signal to the falling edge of the output signal Q_N .

92CS-37133

Fig. 4 - Latch enable propagation delays.



	CD54/74AC	CD54/74ACT
Input Level	V _{CC}	3 V
Input Switching Voltage, V _s	0.5 V _{CC}	1.5 V
Output Switching Voltage, V _s	0.5 V _{CC}	0.5 V _{CC}

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